# Input Parameters for the Simulation of Silicon Solar Cells in 2014

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Abstract—Within the silicon photovoltaics (PV) community, there are many approaches, tools, and input parameters for simulating solar cells, making it difficult for newcomers to establish a complete and representative starting point and imposing high requirements on experts to tediously state all assumptions and inputs for replication. In this review, we address these problems by providing complete and representative input parameter sets to simulate six major types of crystalline silicon solar cells. Where possible, the inputs are justified and up-to-date for the respective cell types, and they produce representative measurable cell characteristics. Details of the modeling approaches that can replicate the simulations are presented as well. The input parameters listed here provide a sensible and consistent reference point for researchers on which to base their refinements and extensions.

*Index Terms*—Photovoltaic (PV) cells, semiconductor device modeling, silicon solar cells, solar cell simulation.

### I. INTRODUCTION

EVICE simulation helps photovoltaics (PV) researchers to understand solar cells, to perform loss analyses, to

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predict how changes to a solar cell design or fabrication procedure will affect its efficiency, and to provide a quantitative foundation to decide on R&D strategies. In their timeless quest to increase accuracy (and reduce complexity), researchers have generated a plethora of equations, algorithms, parameterizations, and programs to simulate solar cells. To the newcomer, the vast array of approaches and possible inputs can be confounding. To the old timer, it is tedious to state all of the inputs and assumptions that ensure a fellow researcher can replicate and test their simulations.

We seek to alleviate these problems by providing a set of inputs to simulate six major types of silicon solar cells. The input sets comprise a starting point for new comers and provide a reference point from which researchers can base their refinements and extensions. The input sets contain the physical properties of the cells, and as such, they are not specific to any modeling approach or software tool.

In addition to providing parameter sets, we apply a specific modeling approach and set of software tools to simulate the optical and electrical behavior of the solar cells. It presents a balance between a high level of detail to cover detrimental physical effects and a low level of complexity to be reproducible and comprehensible to nonexperts. Notably, a subset of the used software tools is freely available, providing a readily accessible way to reproduce the presented results.

The first two parameter sets represent industrial screen-printed solar cells. Due to issues of commercial confidentiality, compromises are made in the selection of values to make public here. Most notably, the inputs that define the emitter profiles and metallization are more representative of recent forerunners to modern industrial cells, rather than those produced in 2014. Nevertheless, the datasets provide a complete and sensible starting point from which readers can critically examine, debate, and substitute inputs. No such compromises are made in the remaining four parameter sets, which represent laboratory-based solar cells whose structures and behavior have been published in detail. A preliminary version of the first parameter set was published in [1].

For completeness, the text that follows is replete with assumptions and qualifiers, many of which require a background in solar cell physics to comprehend. The new comer need not be discouraged by this level of detail. They can commence by downloading the parameter sets from an online solar cell library [2], varying the inputs in the appropriate software and

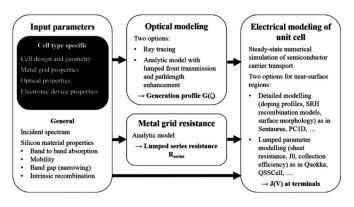


Fig. 1. Flowchart describing the modeling approach; highlighted are the celltype specific input parameters which form the scope of this work.

observing how the efficiency of a particular cell type depends on its physical structure.

### II. MODELING APPROACH

The modeling approach followed in this work is sketched in Fig. 1. It can be divided into optical modeling to derive the generation profile, calculation of a lumped series resistance to represent the metal grid resistive losses, and electrical simulation of an element of symmetry (a unit cell). For the sake of keeping complexity at a moderate level, this approach neglects some full-size effects: perimeter losses, busbar recombination, the distributed nature of the metal grid resistance, and inhomogeneity of the silicon wafer. Details of the assumptions and simplifications are stated in the following sections.

### A. Optical Modeling

The purpose of the optical modeling is to determine the generation profile of electron—hole pairs within the silicon. This requires knowledge of the incident illumination, the surface morphologies, the thickness of the wafer and any films, and the complex refractive index of all materials.

Parameter sets for two modeling approaches are presented. Importantly, both approaches modify the generation profile under textured surfaces such that it approximates the profile under an equivalent planar surface. It greatly simplifies the subsequent electrical modeling to treat the solar cell as having planar surfaces.

The first approach is ray tracing, here performed with *Sentaurus Device* [3] or the Wafer ray tracer on PV Lighthouse [4]. Both are able to directly compute the generation profile  $G(\zeta)$  of electron–hole pairs in the silicon, where  $\zeta$  is defined as the shortest distance to the illuminated surface [5]. The purpose of using  $\zeta$  rather than depth is that it converts the generation profile under a complicated geometry (e.g., random pyramids) to an equivalent generation profile under a planar surface.

The second approach to the optical modeling is to use the front-surface transmission  $T_{\rm ext}(\lambda)$  and the pathlength enhancement  $Z(\lambda)$  as inputs, which are both a function of wavelength  $\lambda$ . As described in detail in [6], those quantities are used to calculate the generation profile by an analytical model similar to the one presented in [7] and are suitable inputs, e.g., for the solar cell simulator Quokka [8]. Furthermore, the related reflection,

absorption, and transmission data are used for comparison to quantum efficiency (QE) measurements of finished solar cells, with the purpose of validating and calibrating the optical and electrical input parameters.

Shading by fingers is represented by nil generation underneath their effective shading width, whereas busbar shading is considered by either a global scaling of the generation profile or a postsimulation scaling of the current density, which gives almost identical results. The influence of altered internal reflectivity at finger and busbar regions is neglected for simplicity. Furthermore, free-carrier absorption and photon reabsorption are neglected or effectively incorporated into rear reflector assumptions to fit measured  $J_{\rm sc}$ .

### B. Metal Grid Resistance

The metal grid resistance is represented by a lumped series resistance value  $R_{\rm series}$ , thereby neglecting the influence of its distributed nature. This can overestimate the fill factor (FF) for cells that have a significant metal resistance, but for the cells presented here, it was concluded from SPICE modeling that the assumption has minimal influence on FF.  $R_{\rm series}$  is derived by analytical modeling, as described in [9], using Grid on PV Lighthouse. Contact resistance is excluded from the lumped series resistance because it is included in the electrical modeling, thereby accounting for related current transfer effects. Busbar resistance is neglected, which is consistent with a high number of measurement probes along the busbar during current–voltage testing. Unless stated otherwise, a rectangular profile of metal fingers is assumed.

### C. Electrical Modeling of the Unit Cell

To derive the current–voltage (I–V) and QE characteristics of the solar cell, electrical modeling of the unit cell is performed by means of steady-state numerical simulation of the semiconductor carrier transport in two or three dimensions. There are essentially two different ways of treating near-surface regions: 1) lumped parameter modeling (i.e., the conductive boundary approach) and 2) detailed modeling.

The first approach has the advantage of being simpler and much faster. The near-surface region is treated as a boundary condition, described by a set of lumped input parameters consisting of the sheet resistance  $R_{\rm sheet}$ , the collection efficiency  $\eta_{\rm c}$ , and a (injection-dependent) recombination parameter  $J_0$  or  $S_{\rm eff}$ . It is well validated for typical wafer-based silicon solar cells and implemented in several software tools, e.g., in Quokka [8], [10], CoBoGUI [11], PC2D [12], and QSSCell [13], [14].

The second approach is more computationally expensive, but it includes the physical nature of the surfaces and immediate subsurface regions. It simulates them by solving a set of best-known physical models that describe the electrical, optical, and thermal properties of the material system. The main inputs for solar devices are the doping profile  $N(\zeta)$ , the surface Shockley–Read–Hall (SRH) recombination parameters  $S_{\rm n}$  and  $S_{\rm p}$ , the surface charge Q, and at times empirical correction factors in case of a textured surface morphology. This approach provides more insight into the detailed operation of the device and must be used when effects within the near-surface regions are investigated. It

is well established and implemented in several software tools, e.g., in Sentaurus Device [3], Atlas [15], EDNA [16], in the Semiconductor Module of Comsol Multiphysics [17], [18] and PC1D [19], [20].

As described in Section II-A, a textured surface is approximated by a planar electrical solution domain, which for the detailed modeling necessitates the introduction of correction factors to reproduce experimentally measured characteristics. Most importantly, the recombination increases due to surface area enlargement, which is addressed by increasing recombination parameters, mainly  $S_{n0}$  and  $S_{p0}$ , and optionally volumetric Auger and SRH recombination by a texture multiplier (typically 1.3–1.7). While the measured  $J_0$  can be reproduced by this approach, an accurate representation of the collection efficiency  $\eta_c$  (ratio of collected and generated carriers within the near-surface region) is difficult to achieve simultaneously. The conductive boundary approach avoids this problem by setting  $J_0$ ,  $R_{\rm sheet}$ , and  $\eta_{\rm c}$  independently of one another to empirically determined values. Due to zero generation underneath fingers,  $\eta_c$  for contacted regions is irrelevant and consequently not given in the input parameter sets.

It is also possible to use a combined approach in which aspects of the cell that cannot be directly measured are first simulated with detailed modeling, and then, the lumped outputs are used in a subsequent conductive boundary model.

In this paper, we describe how each solar cell structure can be consistently simulated with both the lumped parameter and detailed approach. For lumped parameter modeling, we use a combination of EDNA [16] to perform detailed surface modeling (where lumped parameters are not directly available) and *Quokka* [8] for conductive boundary device simulations. Complete detailed modeling is performed with the commercial device simulation software Sentaurus Device [3] or Atlas [15].

In this work, the simulation of the electrical performance of the unit cell neglects some of the specific regions of a real solar cell. Most notable is the impact of the busbar and edge regions. In addition, some solar cells also have solder contact pads that can introduce additional recombination due to the lack of BSF formed. In all of the front-contact simulations presented here (except the PERL cell which has no busbar), the impact of the busbar shading is considered as described in the Section II-A. For simplicity, the recombination impact of these regions is neglected as is any impact from the edge regions. Furthermore, any  $J_{02}$  and  $R_{\rm shunt}$  contributions from edges and busbars are neglected, again for simplicity.

### III. INPUT PARAMETER SETS

The main purpose of this work is to present complete and representative parameter sets for six major silicon solar cell structures. The first two sets are for common commercial solar cells, and the other four sets are laboratory-based solar cells. The input parameters comprise a mixture of measured, modeled, and empirically fitted values, as stated for the individual cell types.

We emphasize that the input parameters cannot provide a precise description of every solar cell of a given structure. The PV industry manufactures cells with a wide distribution of I–V performance, largely due to a wide distribution in the quality

TABLE I
GENERAL INPUT PARAMETERS USED IN THIS WORK

Temperature	298.15 K (25 °C)
free carrier statistics	Fermi–Dirac for highly doped regions Boltzmann for bulk (equals Fermi–Dirac for low doping)
intrinsic carrier density	$8.27\times10^9$ cm $^{-3}$ (calculated from [eq. (3), 23] multiplied by 0.9953 to match $9.65\times10^9$ cm $^{-3}$ at 300 K [24])
bandgap narrowing	no BGN for bulk in conductive boundary modeling, Schenk [25] otherwise
Auger recombination	Richter et al. [26] (300 K)
radiative recombination	$B_{\rm rad} = 4.73 \times 10^{-15} \text{ cm}^3/\text{s} [27] (300 \text{ K})$
mobility	Klaassen [28]
incident spectrum	AM1.5g [29]
optical properties Si	Green [30]

of silicon wafers but due to ongoing improvements in materials, equipment and processes and to temporal variability in production lines as well.

The parameter sets provided for the industry-typical cells (A, B) are necessarily nebulous. They are not generated from any specific solar cell, but are selected to represent a "typical" cell within the wide variety manufactured in industry. The parameter sets do not represent the "state-of-the-art" in 2014, and they will be outdated in the near future. In fact, some inputs could already be considered outdated, a necessary consequence of commercial confidentiality. To supplement the specific values, we therefore provide a value range for those inputs that are well known to have a wide distribution.

The parameter sets for the laboratory-based cells (C–F) are more specific because, with the exception of the heterojunction technology (HJT) cell (D), they have been determined from measurements on a particular experimental solar cell. The inputs for the HJT cell combine properties from different laboratories (not industry). Thus, the laboratory-based cells are very specific to the technology applied by the respective institute and are also not representative of their equivalent industrial solar cells.

Thus, irrespective of the dataset, the reader is encouraged to use these inputs as a sensible and consistent starting point and to substitute their own values where appropriate.

### General Input Parameters

An essential part of the input parameters form the general inputs common to all cell types, including the choice of parameterizations for modeling silicon properties. Table I summarizes the inputs used in this work, mostly as suggested in [21]. Notably, for Auger and radiative recombination, model parameters are valid at 300 K only. However, neglecting their temperature dependence results in minor effect on the simulation result compared with the large effect of the different intrinsic carrier concentration. We accept these inconsistencies and choose 25 °C (298.15 K) to be more representative for standard testing conditions.

An important parameter for the conductive boundary modeling using  $J_0$  values is the effective intrinsic carrier density  $n_{\rm ieff}$ . We use the value of  $n_{\rm ieff} = n_{\rm i} = 8.27 \times 10^9$  cm<sup>-3</sup> (see Table I) in the bulk consistently throughout this work for conductive boundary modeling, neglecting the small amount of bandgap

TABLE II
INPUT PARAMETER SET FOR THE CONVENTIONAL CELL

cell design					
cell size	te 156 mm × 156 mm square thickness 180- $\mu$ m				
front	homogeneous n+ diffusion H-pattern screen-printed				
	metallization				
ear full-area screen-printed and alloyed Al-BSF					
	optics				
front dielectric					
front	Isotexture, modeled by spherical caps with $\omega=60^\circ$ [33]–[35]				
morphology busbar shading	2.5%				
fraction					
effective finger shading width	42 $\mu\text{m}$ (finger width times 70% optical shading factor [44])				
rear	planar with some scattering, modeled by Phong reflection with $R_0 = 0.7$ and $w = 4$ [45], [46]				
	metal grid				
front fingers	75 fingers with 2.08-mm-pitch, $60$ - $\mu$ m-wide, and $12$ - $\mu$ m-high				
	rectangular shape Ag-paste with 4.5- $\mu\Omega$ · cm resistivity				
	contact resistivity $2\text{-m}\Omega \cdot \text{cm}^2$				
	lumped series resistance: $0.312 \ \Omega \cdot cm^2$				
front busbars	3 busbars, 1300-µm-wide and 15-µm-high				
	Ag-paste with 4.5- $\mu\Omega$ · cm resistivity lumped series resistance: neglected				
rear metal	full area Al-paste with $35-\mu\Omega$ · cm resistivity, $30-\mu$ m-high				
	contact resistivity $5\text{-m}\Omega\cdot\text{cm}^2$				
	lumped series resistance: neglected				
-	electrical properties				
bulk	$2$ - $\Omega$ · cm p-type mc mid-gap SRH lifetimes $\tau_{\rm n} = \tau_{\rm p} = 75~\mu{\rm s}$				
front n <sup>+</sup> diffusion	1 1				
	recombination parameter $J_0$				
	passivated: 201 fA/cm <sup>2</sup> (150–300)				
	contacted: 204 fA/cm <sup>2</sup> (200–600)				
	depth 0.39 μm				
	collection efficiency 0.85 (0.8–0.9). detailed inputs				
	doping profile				
	total and active concentration from [38], see Appendix B				
	surface SRH				
	passivated: $S_p = 6.63 \times 10^6$ cm/s, $S_n = 1 \times 10^7$ cm/s				
	(derived from [39] with texture multiplier of 1.73) contacted: $S_p = S_n = 1 \times 10^7$ cm/s (thermal velocity)				
	volume SRH				
	modeled via inactive phosphorus profile according to [39]				
+ .	and a texture multiplier of 1.73				
rear p <sup>+</sup> region	lumped inputs sheet resistance $30 \Omega (20-40)$				
	recombination parameter $J_0 = 517 \text{ fA/cm}^2 (300-700)$				
	depth 7- $\mu$ m				
	collection efficiency 0.7				
	detailed inputs doping profile				
	measured active concentration from [40] with				
	incomplete ionization model from [45], see Appendix B				
	surface SRH				
	$S_{\rm p} = S_{\rm n} = 1 \times 10^7 \text{ cm/s (thermal velocity)}$				
	volume SRH modeled as in [41] with parameters in [42]				
	modeled as in [41] with parameters in [42]				

narrowing.  $J_0$  values derived with a different assumption of  $n_{\text{ieff}}$  are scaled according to  $J_0/n_{\text{ieff}}^2 = \text{const}$  [22].

### A. Conventional (Industry Typical Properties): p-Type Full-Area Rear-Alloyed Cell with Screen-Printed Metallization

Solar cells with a conventional design are presently the dominant cell type in large-scale industrial manufacturing [31]. The

models presented here are based on values obtained from both the literature, as well as various industry sourced cells whose specific details remain hidden for commercial reasons. In general, there are several possible varieties of this cell type. Most notably, the substrate may be either multicrystalline (standard or high performance) or monocrystalline Czochralski (Cz). Here, we have chosen standard multicrystalline material to demonstrate both a simple bulk model for this material as well as how to incorporate an isotextured front surface. The emitter may be formed with either a "standard" or "high-efficiency" approach; see, for example, [32]. We have chosen the "standard" approach to demonstrate how to model the impact of Si-P precipitation on cell performance. It should be noted that, particularly for conventional screen print cells on monocrystalline material, it is likely that the majority of production cells now use the highefficiency emitter approach. For the input parameters to such an emitter, see the passivated emitter rear cell (PERC) cell in the next section. Finally, the screen-print fingers themselves also have several varieties. This includes single print and double print, as well as an alternative in stencil printing. Since the overwhelming majority of production cells are currently manufactured by the first option, the inputs we present for the front contact represent a typical single-print 3 busbar H pattern with an average finger width that is consistent with the 2014 ITRPV [31].

The front-surface optical properties of these cells are dominated by the isotexture. Although this surface topology is rather irregular and depends strongly on the manufacturing process, it is possible to quantify the photogeneration and parasitic absorption of the cell with standard ray tracing, assuming a 3-D symmetry element with a top shape of a spherical cap spanning a characteristic angle [33]–[35]. The rear interface is approximated with a planar geometry, causing a moderate amount of scattering described with Phong's model [36].

The isotexturing also increases the surface area and, hence, the  $J_0$  of the emitter, typically by a factor of about 1.2. In this simulation example,  $J_0$  derived by detailed modeling in the planar simulation domain without correction factors consequently needs to be 167 fA/cm<sup>2</sup> to represent the target value of 200 fA/cm<sup>2</sup>. This increase in  $J_0$  cannot be reproduced by simply increasing the SRH recombination velocity  $S_p$  of the front surface and the capture cross section  $\sigma_{\rm D}$  of the inactive phosphorus by a factor of 1.2, because the limited carrier collection efficiency causes nonlinearities. In our example, a suitable multiplication factor turned out to be 1.73 (coincidentally the surface area enhancement factor of ideal pyramidal texture). This quantifies  $V_{oc}$  rather precisely, but then underestimates the internal quantum efficiency in the UV and blue part of the spectrum. For the conductive boundary modeling, we therefore do not use the collection efficiency resulting from the detailed modeling of this particular emitter but, rather, a typical constant value of 0.85 [32], [37].

The "standard" heavily doped emitter is modeled using both a profile of active as well as inactive dopants as shown in Fig. 6 in Appendix B. The difference between these two profiles is inactive phosphorus (interstitial P clusters and possibly various forms of precipitates), which then leads to a highly localized degradation of the carrier lifetime. The full details of these profiles and their impact on recombination can be found in [38]

and [39]. Notably, we neglect the effects of metal paste etching and silver crystallites under at the contacted emitter regions, but rather assume identical doping profiles with thermal surface recombination velocity. This may result in an unrealistically low  $J_0$  for the contacted emitter, which has however minor influence on the simulated cell characteristics.

Similarly, we present a detailed model for the back surface field. This work has assumed that the boron concentration of the screen-printed pastes is negligible (which may not be true for high-efficiency rear-side pastes), and therefore, the BSF is entirely formed from Al. The exact profile used for the BSF is obtained from [40] and is shown in Fig. 7 in Appendix B. The modeling accounts for incomplete ionization and Al–O complex recombination via the models presented in [41], with defect parameters taken from [42].

The lifetime within the bulk of multicrystalline material is dominated by a variety of defects, which are expected to vary greatly from wafer to wafer. For this reason, we propose here a simplification which will allow the simulation of the basic underlying performance of the device architecture itself. Neglected are the spatial variations of the bulk lifetime due to the different grains, grain boundaries, edge contaminated regions, and defect clusters. It is worth noting that the relative impact of all of the inputs will be modulated by this underlying material quality. However, specific strategies to account for this are beyond the scope of this paper. Thus, to provide a basic model for the bulk of a standard mc-Si wafer, we use here a single SRH defect at mid-band with  $\tau_{\rm n}=\tau_{\rm p}=75~\mu{\rm s}$ . The input parameters for the conventional cell are summarized in Table II.

### B. Passivated Emitter Rear Cell (Industry Typical Properties): Monocrystalline p-Type Cell With Local Al-BSF and Screen-Printed Metallization

PERC cells are presently being introduced into mass production to increase cell efficiency. They improve upon the conventional cell (described above) by replacing the rear-surface full-area Al-BSF with a stack of passivation layers and localized contacts; in order to gain benefits from the improved rear, the emitter must be improved as well. The localized contact regions are typically formed by locally laser ablating the rear dielectric film and then firing specialized screen-printed Al paste through the openings to form localized BSF regions.

In principle, the rear of the PERC cell architecture is somewhat independent of the choice of front-surface properties. As such, it would be possible to substitute the values provided here with those from the previous section. However, the low recombination achieved at the rear surface means that this type of cell is more sensitive to increased recombination in the bulk or at the front surface. We, therefore, model it with a "high-efficiency" emitter and good-quality monocrystalline Cz silicon substrates. The SRH lifetime parameters are chosen from [47] and do not include the recent improvements made in stabilizing the B–O complex.

The optical losses are calculated with standard ray tracing assuming a classic single KOH textured pyramid but random shifts of the rays to mimic the random placement of the pyramids. The optical properties of the rear interface are important in PERC cells. In this example, the scattering and parasitic absorption are ray traced with the tilted-mirrors model [48], [49]. The optical properties depend strongly on the thickness of the dielectric between Si and Al. Here, a 100-nm  $SiN_x$  is chosen (having the same refractive index as the front AR coating for simplicity), on top of 10-nm plasma-enhanced chemical vapor deposition (PECVD)  $AIO_x$ .

For confidentiality reasons, the "high-efficiency" emitter used here does not represent an actual manufactured one. It is derived from the "standard" emitter as described in the above conventional cell by omitting the first 30 nm of the doping profile, representing an etch-back process commonly used in industry for this purpose, and as such might be significantly different to typical high-efficiency emitter profiles. The KOH-texturing increases the surface area of the emitter by a factor of approximately 1.7. It is shown in [50], however, that the accompanying increase in  $J_0$  can be reasonably compared with the increase in case of isotexturing. Therefore, for calculating the SRH recombination velocity  $S_p$  of the front side and the capture cross section  $\sigma_{\rm p}$  of the inactive phosphorus, we choose a texture multiplier of 1.35, which is used to account for the increase in  $J_0$ of many industrial emitters after isotexturing. Detailed modeling of this virtual "high-efficiency" emitter results in a typical decrease of  $J_0$  compared with the standard emitter (while still having a slightly higher than typical absolute value) but with a notably relatively high sheet resistance  $R_{\rm sheet}$ . Due to the latter, the simulated resistive losses in the emitter may be larger than typical. As explained in the conventional cell above, the collection efficiency is set independent from the detailed modeling results to a value of 0.95 typical for a high-efficiency emitter.

Of critical importance to the performance of a PERC cell is the design of the rear-side contact pattern. The localized BSF regions are in this case formed as lines but are often also formed as an array of points. The selection of the width and pitch of these lines is a tradeoff between resistive and recombination losses. From the literature, it is clear that there is a wide variety of values for the recombination at the rear surface and within these localized contact regions. However, insufficient reliable data have been published to date to deduce a justifiable range for  $J_0$  of the localized BSF, which is therefore omitted from Table III despite its large variation. The amount of recombination within the device may also be affected by void formation, which is not accounted for here. In this example, we neglect lateral variations within the localized BSF regions and apply the full-area Al-BSF profile from the conventional cell above thinned by 3  $\mu$ m to represent the typically shallower depth and higher recombination of a localized BSF. The input parameters for the PERC cell are summarized in Table III.

### C. n-PASHA (ECN): Bifacial n-Type Cell with Screen- and Stencil-Printed Metallization

The n-PASHA cell developed at ECN [53], along with its industrial equivalents PANDA of Yingli Solar [54], is one of the most prominent industrial bifacial cells. The models and input sets presented here for the n-Pasha cell have been chosen

TABLE III
INPUT PARAMETER SET FOR THE PERC CELL

cell design				
cell size front rear	156 mm $\times$ 156 mm pseudosquare thickness 180 $\mu$ m homogeneous n $^+$ diffusion H-pattern screen-printed metallization undiffused and passivated line local p $^+$ alloyed Al-BSF, 120 $\mu$ m wide, 850 $\mu$ m pitch			
	optics			
front dielectric front morphology	70-nm PECVD $SiN_x$ [43] ( $n = 1.99$ ) random pyramids			
rear dielectrics	10-nm PECVD ${\rm Al_2O_3}$ [51] (inner film) 100-nm PECVD ${\rm SiN_x}$ [43] ( $n=1.99$ ) (outer film)			
busbar shading	modeled by "strong planarization" case of the tilted-mirrors model [48], [49] 2.5%			
fraction effective finger	$42~\mu\mathrm{m}$ (finger width times 70% optical shading factor [44])			
shading width	metal grid			
front fingers	91 fingers with 1.7 mm pitch, 60 $\mu$ m wide, and 12 $\mu$ m high, rectangular shape			
	Ag-paste with $4.5 - \mu\Omega \cdot cm$ resistivity contact resistivity $2 \text{ m}\Omega \cdot cm^2$ lumped series resistance: $0.252 \Omega \cdot cm^2$			
front busbars	3 busbars, 1300- $\mu$ m-wide and 15- $\mu$ m-high Ag-paste with 4.5- $\mu\Omega$ · cm resistivity lumped series resistance: neglected			
rear metal	full area Al-paste with 35- $\mu$ $^{O}$ · cm resistivity, 30- $\mu$ m-high contact resistivity 5-m $^{O}$ · cm <sup>2</sup> lumped series resistance: neglected			
	electrical properties			
bulk	2- $\Omega$ · cm p-type CZ mid-gap SRH lifetimes $ au_{\rm n}=$ 371 $\mu{\rm s}$ and $ au_{\rm p}=$ 3710 $\mu{\rm s}$ derived			
front n <sup>+</sup> diffusion	from [47] lumped inputs sheet resistance $162 \Omega (90-160)^*$			
	recombination parameter $J_0$ passivated: 168 fA/cm <sup>2</sup> (80–140)* contacted: 595 fA/cm <sup>2</sup> (400–700)			
	depth $0.36 \mu m$ collection efficiency $0.95$ detailed inputs			
	doping profile total and active concentration from [38] with 30-nm etch-back, see Appendix B surface SRH			
	passivated: $S_{\rm p}=4.86\times 10^5~{\rm cm/s}$ , $S_{\rm n}=1\times 10^7~{\rm cm/s}$ (derived from [39] with texture multiplier of 1.35) contacted: $S_{\rm p}=S_{\rm n}=1\times 10^7~{\rm cm/s}$ (thermal velocity)			
	volume SRH modeled via inactive phosphorus profile according to [39] and a texture multiplier of 1.35			
rear p <sup>+</sup> region	lumped inputs sheet resistance $61-\Omega$ recombination parameter $J_0 = 795 \text{ fA/cm}^2$			
	depth 4 $\mu$ m collection efficiency 0.9 detailed in puts			
	doping profile measured active concentration from [40] with incomplete ionization model from [45], 3-\mu m etch-back; see Appendix B surface SRH			
	$S_{\rm p}=S_{\rm n}=1\times 10^7$ cm/s (thermal velocity) volume SRH modeled as in [41] with parameters in [42]			

### TABLE III (CONTINUED)

passivated rear	lumped inputs  recombination parameter $J_0 = 13.1 \text{ fA/cm}^2$
	detailed inputs surface SRH and charge $S_{\rm p}=78~{\rm cm/s}, S_{\rm n}=1.08\times10^5~{\rm cm/s}, Q=-3\times10^5~{\rm cm/s}$
	$10^{12} \text{ cm}^{-2} \text{ from [52] with } D_{\rm it} = 6 \times 10^{17} \text{ cm}^{-2} \cdot \text{eV}^{-1}$ (midgap)

\*The lumped input parameters for the emitter being out-of-range of typical values is caused by the enforced consistency with the detailed modeling, which input parameters deviate from an industry-typical high-efficiency emitter due to confidentiality reasons (see text for more information)

such that the optical, recombination, and resistive properties of laboratory cells manufactured at ECN are well represented. A slightly different description of the n-Pasha cell was given in [55].

The reported  $J_0$  values were taken from lifetime measurements. The reported  $S_{\rm p0}$ ,  $S_{\rm n0}$  values were adapted to obtain the measured  $J_0$ . To account for the textured surface, an enhancement factor of 1.7 was used both for the Auger and surface recombination. The present parameters still suggest that optimization of the surface is possible.

It was found that in order to describe recombination at the contacts, a local etch-back of the profile must be assumed [49]. Such a uniform effective etch-back is an idealization of the actual damage that is caused by fire-through metallization, especially under the Ag–Al contacts on the emitter. The effective etch depths are chosen to match the difference in implied  $V_{\rm oc}$  of the cell before metallization and the measured  $V_{\rm oc}$  after metallization.

The n-Pasha cell has a random pyramid texture at the front and rear surfaces. A textured rear is required to obtain a high bifaciality factor. In the present model, the rear dielectric layer is not treated explicitly. A Lambertian rear reflector was assumed, and the reflectivity was adapted to match the measured  $J_{\rm sc}$ . In the assumption for the rear reflector, two opposing effects are lumped: the significant free-carrier absorption within the two full-area diffusions, and the current gain from the reflective chuck used in the measurement.

Fig. 4 shows that the recombination at MPP is rather evenly distributed over the bulk, emitter and BSF, although recombination at the metallized areas is relatively large. Further optimization of contacts and diffused regions would make the cell efficiency more dependent on the bulk quality. The rear n+ diffusion of the n-Pasha cell has a large contribution to the resistive losses, which is accepted in order to keep the shaded area small for high bifaciality. The input parameters for the n-PASHA cell are summarized in Table IV.

### D. Heterojunction Technology (Projected): n-Type Heterojunction Cell with Screen-Printed Metallization

The HJT was successfully first industrialized by Sanyo, now Panasonic, and holds the current efficiency record for a

TABLE IV INPUT PARAMETER SET FOR THE N-PASHA CELL

cell design				
cell size	156 mm × 156 mm pseudosquare			
Front	thickness 180- $\mu$ m homogeneous p+ diffusion			
Tront	H-pattern stencil-printed metallization			
Rear	homogeneous n+ diffusion			
	H-pattern screen-printed metallization			
-	optics			
front and rear dielectric	70-nm PECVD SiN $_x$ [43] ( $n = 1.99$ )			
front and rear morphology	random pyramids, 54.3° characteristic angle, 5- $\mu$ m texture height			
rear optics	modeled by Lambertian rear reflector with effective $R = 0.78$			
busbar shading	and $T=0.22$ to match $J_{\rm sc}$ measured with a reflective chuck. 2.86%			
fraction	2.00 //			
effective finger shading width	31.5 $\mu$ m (finger width times 70% optical shading factor [44])			
	metal grid			
front fingers	72 fingers with 2.05-mm-pitch, 45- $\mu$ m-wide, and 30- $\mu$ m-high			
	Al-Ag-paste with 4.7- $\mu\Omega$ · cm resistivity contact resistivity 3-m $\Omega$ · cm <sup>2</sup> (estimate)			
	lumped series resistance: $0.185 \Omega \text{cm}^2$			
front and rear	3 busbars, 1500- $\mu$ m-wide and 10- $\mu$ m-high Ag-paste with 3- $\mu$ $\Omega$ · cm resistivity, noncontacting			
busbars	lumped series resistance: neglected			
rear fingers	144 fingers with 1.025-mm-pitch, $100-\mu$ m-wide, and			
	$10$ - $\mu$ m-high Ag-paste with $3$ - $\mu\Omega$ · cm resistivity			
	contact resistivity $3-m\Omega \cdot cm^2$ (estimate)			
	lumped series resistance: $0.083~\Omega \cdot cm^2$			
	electrical properties			
bulk	2.7 Ω · cm n-type			
front p+	mid-gap SRH lifetimes $\tau_{\rm n} = \tau_{\rm p} = 1000 \ \mu \text{s}$ lumped inputs			
diffusion	sheet resistance $68-\Omega$			
	recombination parameter $J_0$			
	passivated: 63 fA/cm <sup>2</sup>			
	contacted: 1836 fA/cm <sup>2</sup>			
	depth 0.55 // m			
	depth 0.55 $\mu$ m collection efficiency = 1			
	collection efficiency = 1 detailed inputs			
	collection efficiency = 1  detailed inputs  active doping profile			
	collection efficiency = 1  detailed inputs  active doping profile  superposition of two Gaussians: $6.19 \times 10^{19}$ cm <sup>-3</sup> /			
	collection efficiency = 1 detailed inputs active doping profile superposition of two Gaussians: $6.19 \times 10^{19}$ cm <sup>-3</sup> / $5.77 \times 10^{19}$ cm <sup>-3</sup> peak, $0.045 \ \mu$ m/0.117 $\mu$ m peak depth, $0.048 \ \mu$ m/0.135 $\mu$ m depth factor (PC1D definition)			
	collection efficiency = 1 detailed inputs active doping profile superposition of two Gaussians: $6.19 \times 10^{19}$ cm <sup>-3</sup> / $5.77 \times 10^{19}$ cm <sup>-3</sup> peak, $0.045 \ \mu$ m/0.117 $\mu$ m peak depth, $0.048 \ \mu$ m/0.135 $\mu$ m depth factor (PC1D definition) 200-nm etch assumed under contacts			
	collection efficiency = 1 detailed inputs active doping profile superposition of two Gaussians: $6.19 \times 10^{19}$ cm <sup>-3</sup> / $5.77 \times 10^{19}$ cm <sup>-3</sup> peak, $0.045 \ \mu$ m/0.117 $\mu$ m peak depth, $0.048 \ \mu$ m/0.135 $\mu$ m depth factor (PC1D definition)			
	collection efficiency = 1 $\begin{array}{l} \textit{detailed inputs} \\ \textit{active doping profile} \\ \textit{superposition of two Gaussians: } 6.19 \times 10^{19}~\text{cm}^{-3} / \\ 5.77 \times 10^{19}~\text{cm}^{-3} \textit{peak}, 0.045~\mu\text{m}/0.117~\mu\text{m} \textit{peak depth}, \\ 0.048~\mu\text{m}/0.135~\mu\text{m} \textit{depth factor (PC1D definition)} \\ 200-\text{nm} \textit{etch assumed under contacts} \\ \textit{surface SRH} \\ \textit{texture multiplier of } 1.7 \\ \textit{passivated: } S_p = 2 \times 10^3~\text{cm/s}, S_n = 2 \times 10^3~\text{cm/s} \end{array}$			
	collection efficiency = 1 $\begin{array}{l} \textit{detailed inputs} \\ \textit{active doping profile} \\ \textit{superposition of two Gaussians: } 6.19 \times 10^{19}  \text{cm}^{-3} / \\ 5.77 \times 10^{19}  \text{cm}^{-3}  \text{peak, } 0.045  \mu \text{m/0.117 }  \mu \text{m}  \text{peak depth, } \\ 0.048  \mu \text{m/0.135 }  \mu \text{m}  \text{depth factor (PC1D definition)} \\ 200\text{-nm etch assumed under contacts} \\ \textit{surface SRH} \\ \textit{texture multiplier of 1.7} \\ \textit{passivated: } S_p = 2 \times 10^3  \text{cm/s, } S_n = 2 \times 10^3  \text{cm/s} \\ \textit{contacted: } S_p = S_n = 1 \times 10^7  \text{cm/s (thermal velocity)} \\ \end{array}$			
	collection efficiency = 1 $\begin{array}{l} \textit{detailed inputs} \\ \textit{active doping profile} \\ \textit{superposition of two Gaussians: } 6.19 \times 10^{19}~\text{cm}^{-3} / \\ 5.77 \times 10^{19}~\text{cm}^{-3} \textit{peak}, 0.045~\mu\text{m}/0.117~\mu\text{m} \textit{peak depth}, \\ 0.048~\mu\text{m}/0.135~\mu\text{m} \textit{depth factor (PC1D definition)} \\ 200\text{-nm etch assumed under contacts} \\ \textit{surface SRH} \\ \textit{texture multiplier of 1.7} \\ \textit{passivated: } S_p = 2 \times 10^3~\text{cm/s}, S_n = 2 \times 10^3~\text{cm/s} \\ \textit{contacted: } S_p = S_n = 1 \times 10^7~\text{cm/s (thermal velocity)} \\ \textit{volume recombination} \end{array}$			
	collection efficiency = 1 $\begin{array}{l} \textit{detailed inputs} \\ \textit{active doping profile} \\ \textit{superposition of two Gaussians: } 6.19 \times 10^{19}  \text{cm}^{-3} / \\ 5.77 \times 10^{19}  \text{cm}^{-3}  \text{peak, } 0.045  \mu \text{m/0.117 }  \mu \text{m}  \text{peak depth, } \\ 0.048  \mu \text{m/0.135 }  \mu \text{m}  \text{depth factor (PC1D definition)} \\ 200\text{-nm etch assumed under contacts} \\ \textit{surface SRH} \\ \textit{texture multiplier of 1.7} \\ \textit{passivated: } S_p = 2 \times 10^3  \text{cm/s, } S_n = 2 \times 10^3  \text{cm/s} \\ \textit{contacted: } S_p = S_n = 1 \times 10^7  \text{cm/s (thermal velocity)} \\ \end{array}$			
rear n+	collection efficiency = 1 $\begin{array}{l} \textit{detailed inputs} \\ \textit{active doping profile} \\ \textit{superposition of two Gaussians: } 6.19 \times 10^{19} \text{ cm}^{-3} / \\ 5.77 \times 10^{19} \text{ cm}^{-3} \text{ peak, } 0.045 \ \mu\text{m}/0.117 \ \mu\text{m peak depth, } \\ 0.048 \ \mu\text{m}/0.135 \ \mu\text{m depth factor (PC1D definition)} \\ 200\text{-nm etch assumed under contacts} \\ \textit{surface SRH} \\ \textit{texture multiplier of } 1.7 \\ \textit{passivated: } S_p = 2 \times 10^3 \text{ cm/s, } S_n = 2 \times 10^3 \text{ cm/s} \\ \textit{contacted: } S_p = S_n = 1 \times 10^7 \text{ cm/s (thermal velocity)} \\ \textit{volume recombination} \\ \textit{SRH same as bulk} \\ \textit{texture multiplier of } 1.7 \text{ for Auger} \\ \textit{lumped inputs} \end{array}$			
rear n+ diffusion	collection efficiency = 1 $\begin{array}{l} \textit{detailed inputs} \\ \textit{active doping profile} \\ \textit{superposition of two Gaussians: } 6.19 \times 10^{19}~\text{cm}^{-3} / \\ 5.77 \times 10^{19}~\text{cm}^{-3} \textit{peak}, 0.045~\mu\text{m}/0.117~\mu\text{m} \textit{peak depth}, \\ 0.048~\mu\text{m}/0.135~\mu\text{m} \textit{depth factor (PC1D definition)} \\ 200\text{-nm etch assumed under contacts} \\ \textit{surface SRH} \\ \textit{texture multiplier of } 1.7 \\ \textit{passivated: } S_p = 2 \times 10^3~\text{cm/s}, S_n = 2 \times 10^3~\text{cm/s} \\ \textit{contacted: } S_p = S_n = 1 \times 10^7~\text{cm/s} \textit{ (thermal velocity)} \\ \textit{volume recombination} \\ \textit{SRH same as bulk} \\ \textit{texture multiplier of } 1.7~\text{for Auger} \\ \textit{lumped inputs} \\ \textit{sheet resistance } 171~\Omega \\ \end{array}$			
	collection efficiency = 1 $\begin{array}{l} \textit{detailed inputs} \\ \textit{active doping profile} \\ \textit{superposition of two Gaussians: } 6.19 \times 10^{19} \text{ cm}^{-3} / \\ 5.77 \times 10^{19} \text{ cm}^{-3} \text{ peak, } 0.045 \ \mu\text{m}/0.117 \ \mu\text{m peak depth, } \\ 0.048 \ \mu\text{m}/0.135 \ \mu\text{m depth factor (PC1D definition)} \\ 200\text{-nm etch assumed under contacts} \\ \textit{surface SRH} \\ \textit{texture multiplier of } 1.7 \\ \textit{passivated: } S_p = 2 \times 10^3 \text{ cm/s, } S_n = 2 \times 10^3 \text{ cm/s} \\ \textit{contacted: } S_p = S_n = 1 \times 10^7 \text{ cm/s (thermal velocity)} \\ \textit{volume recombination} \\ \textit{SRH same as bulk} \\ \textit{texture multiplier of } 1.7 \text{ for Auger} \\ \textit{lumped inputs} \end{array}$			
	collection efficiency = 1 $\begin{array}{l} \textit{detailed inputs} \\ \textit{active doping profile} \\ \text{superposition of two Gaussians: } 6.19 \times 10^{19}~\text{cm}^{-3}/\\ 5.77 \times 10^{19}~\text{cm}^{-3} \text{peak, } 0.045~\mu\text{m/0.117}~\mu\text{m peak depth, } 0.048~\mu\text{m/0.135}~\mu\text{m depth factor (PC1D definition)} \\ 200\text{-nm etch assumed under contacts} \\ \textit{surface SRH} \\ \text{texture multiplier of } 1.7 \\ \text{passivated: } S_p = 2 \times 10^3~\text{cm/s, } S_n = 2 \times 10^3~\text{cm/s} \\ \text{contacted: } S_p = S_n = 1 \times 10^7~\text{cm/s (thermal velocity)} \\ \textit{volume recombination} \\ \text{SRH same as bulk} \\ \text{texture multiplier of } 1.7~\text{for Auger} \\ \textit{lumped inputs} \\ \text{sheet resistance } 171~\Omega \\ \text{recombination parameter } J_0 \\ \text{passivated: } 103~\text{fA/cm}^2 \\ \text{contacted: } 1101~\text{fA/cm}^2 \\ \end{array}$			
	collection efficiency = 1 $\begin{array}{l} \textit{detailed inputs} \\ \textit{active doping profile} \\ \text{superposition of two Gaussians: } 6.19 \times 10^{19}~\text{cm}^{-3} / \\ 5.77 \times 10^{19}~\text{cm}^{-3} \text{ peak, } 0.045~\mu\text{m/}0.117~\mu\text{m} \text{ peak depth, } \\ 0.048~\mu\text{m/}0.135~\mu\text{m} \text{ depth factor (PC1D definition)} \\ 200\text{-nm etch assumed under contacts} \\ \textit{surface SRH} \\ \text{texture multiplier of } 1.7 \\ \text{passivated: } S_p = 2 \times 10^3~\text{cm/s, } S_n = 2 \times 10^3~\text{cm/s} \\ \text{contacted: } S_p = S_n = 1 \times 10^7~\text{cm/s (thermal velocity)} \\ \textit{volume recombination} \\ \text{SRH same as bulk} \\ \text{texture multiplier of } 1.7~\text{for Auger} \\ \textit{lumped inputs} \\ \text{sheet resistance } 171~\Omega \\ \text{recombination parameter } J_0 \\ \text{passivated: } 103~\text{fA/cm}^2 \\ \text{contacted: } 1101~\text{fA/cm}^2 \\ \text{depth } 0.4~\mu\text{m} \\ \end{array}$			
	collection efficiency = 1 detailed inputs active doping profile superposition of two Gaussians: $6.19 \times 10^{19}  \mathrm{cm^{-3}}/5.77 \times 10^{19}  \mathrm{cm^{-3}}$ peak, $0.045  \mu \mathrm{m}/0.117  \mu \mathrm{m}$ peak depth, $0.048  \mu \mathrm{m}/0.135  \mu \mathrm{m}$ depth factor (PC1D definition) 200-nm etch assumed under contacts surface SRH texture multiplier of 1.7 passivated: $S_\mathrm{p} = 2 \times 10^3  \mathrm{cm/s}$ , $S_\mathrm{n} = 2 \times 10^3  \mathrm{cm/s}$ contacted: $S_\mathrm{p} = S_\mathrm{n} = 1 \times 10^7  \mathrm{cm/s}$ (thermal velocity) volume recombination SRH same as bulk texture multiplier of 1.7 for Auger lumped inputs sheet resistance 171 $\Omega$ recombination parameter $J_0$ passivated: $103  \mathrm{fA/cm^2}$ contacted: $1101  \mathrm{fA/cm^2}$ depth $0.4  \mu \mathrm{m}$ collection efficiency = $1$			
	collection efficiency = 1 detailed inputs active doping profile superposition of two Gaussians: $6.19 \times 10^{19}  \mathrm{cm}^{-3} / 5.77 \times 10^{19}  \mathrm{cm}^{-3} / \mathrm{peak}$ , $0.045  \mu \mathrm{m}/0.117  \mu \mathrm{m}$ peak depth, $0.048  \mu \mathrm{m}/0.135  \mu \mathrm{m}$ depth factor (PC1D definition) 200-nm etch assumed under contacts surface SRH texture multiplier of 1.7 passivated: $S_{\mathrm{p}} = 2 \times 10^3  \mathrm{cm/s}$ , $S_{\mathrm{n}} = 2 \times 10^3  \mathrm{cm/s}$ contacted: $S_{\mathrm{p}} = S_{\mathrm{n}} = 1 \times 10^7  \mathrm{cm/s}$ (thermal velocity) volume recombination SRH same as bulk texture multiplier of 1.7 for Auger lumped inputs sheet resistance 171 $\Omega$ recombination parameter $J_0$ passivated: $103  \mathrm{fA/cm^2}$ contacted: $1101  \mathrm{fA/cm^2}$ depth $0.4  \mu \mathrm{m}$ collection efficiency = 1 detailed inputs active doping profile			
	collection efficiency = 1 detailed inputs active doping profile superposition of two Gaussians: $6.19 \times 10^{19}  \mathrm{cm}^{-3} / 5.77 \times 10^{19}  \mathrm{cm}^{-3} / \mathrm{peak}, 0.045  \mu \mathrm{m}/0.117  \mu \mathrm{m}$ peak depth, $0.048  \mu \mathrm{m}/0.135  \mu \mathrm{m}$ depth factor (PC1D definition) 200-nm etch assumed under contacts surface SRH texture multiplier of 1.7 passivated: $S_{\mathrm{p}} = 2 \times 10^3  \mathrm{cm/s},  S_{\mathrm{n}} = 2 \times 10^3  \mathrm{cm/s}$ contacted: $S_{\mathrm{p}} = S_{\mathrm{n}} = 1 \times 10^7  \mathrm{cm/s}$ (thermal velocity) volume recombination SRH same as bulk texture multiplier of 1.7 for Auger lumped inputs sheet resistance 171 $\Omega$ recombination parameter $J_0$ passivated: $103  \mathrm{fA/cm^2}$ contacted: $1101  \mathrm{fA/cm^2}$ depth $0.4  \mu \mathrm{m}$ collection efficiency = 1 detailed inputs active doping profile superposition of two Gaussians: $8.75 \times 10^{19}  \mathrm{cm}^{-3}/$			
	collection efficiency = 1 detailed inputs active doping profile superposition of two Gaussians: $6.19 \times 10^{19}  \mathrm{cm}^{-3} / 5.77 \times 10^{19}  \mathrm{cm}^{-3} / \mathrm{peak}$ , $0.045  \mu \mathrm{m}/0.117  \mu \mathrm{m}$ peak depth, $0.048  \mu \mathrm{m}/0.135  \mu \mathrm{m}$ depth factor (PC1D definition) 200-nm etch assumed under contacts surface SRH texture multiplier of 1.7 passivated: $S_{\mathrm{p}} = 2 \times 10^3  \mathrm{cm/s}$ , $S_{\mathrm{n}} = 2 \times 10^3  \mathrm{cm/s}$ contacted: $S_{\mathrm{p}} = S_{\mathrm{n}} = 1 \times 10^7  \mathrm{cm/s}$ (thermal velocity) volume recombination SRH same as bulk texture multiplier of 1.7 for Auger lumped inputs sheet resistance 171 $\Omega$ recombination parameter $J_0$ passivated: $103  \mathrm{fA/cm^2}$ contacted: $1101  \mathrm{fA/cm^2}$ depth $0.4  \mu \mathrm{m}$ collection efficiency = 1 detailed inputs active doping profile			

### TABLE IV (CONTINUED)

20-nm etch assumed under contacts surface~SRH texture multiplier of 1.7 passivated:  $S_{\rm p}=S_{\rm n}=6\times10^4~{\rm cm/s}$  contacted:  $S_{\rm p}=S_{\rm n}=1\times10^7~{\rm cm/s}$  (thermal velocity) volume~recombination SRH same as bulk texture multiplier of 1.7 for Auger

nonconcentrated single-junction silicon solar cell of 25.6% using an IBC design [56]. With a conventional bifacial design, the corresponding heterojunction cell efficiency record (again achieved by Panasonic) is 24.7% [57]. As a comprehensive characterization and description of their device properties is publicly not available, the stated input parameter set describes a theoretical cell, which essentially combines cell design and electrical properties of thin-film a-Si:H layers and interfaces as optimized, measured, and simulated at SERIS [58], [59], with the optical a-Si:H properties and the TCO properties as published by EPFL [60], [61]. For best consistency, we also employ a value for contact resistivity between Ag-paste fingers on this particular TCO, as published in [62].

While not representing a physical manifestation of a real cell, all individual properties and cell characteristics are within reasonable limits of what is typically achieved at research institutes, highlighting common characteristics and loss mechanisms of HJT cells. A notable deviation of the presented laboratory cell design from an industrial HJT design is the full-area silver-based rear metallization, which in industry is commonly replaced by an H-pattern screen printed metallization for bifaciality and cost reasons.

The corresponding simulation input parameters are calibrated twofold: first using published input parameters for heterojunction solar cells by Rahmouni [63] reproducing published results from Panasonic [64] (reporting 20.4% efficiency at that time) (see [Table 4.1, 50]), and second, calibrated toward measured injection-dependent effective carrier lifetime curves of symmetrically passivated silicon wafers using heterojunction silicon thin-film layers as developed and characterized at SERIS (see [Tables 4.2 and 4.4, 50]) stated also in Appendix A.

Please note that especially the optical properties of the TCO have to be improved in order reach higher short-circuit current densities (i.e., compare  $J_{\rm sc}$  values in the order of 37 mA  $\cdot$  cm<sup>-2</sup> as reported by Rahmouni/Taguchi [63], [64] and also if using the optical TCO and a-Si:H data published by EPFL [60], [61] to a  $J_{\rm sc}$  of 39.5 mA  $\cdot$  cm<sup>-2</sup>, as recently reported by Panasonic [57]). Furthermore, the modeling assumes that the workfunction match of the TCO has been achieved, and thus, no TCO-induced band-bending reaching into the silicon bulk has to be considered. The optical properties depend strongly on the thickness and dielectric properties of the TCO and a-Si:H used. Here, a 70-nm-thick ITO is chosen as TCO, i.e., using optical TCO and a-Si:H data as published by Black and McIntosh [52]. Again note that currently the calibration toward measured lifetime samples

did not consider TCO. After a subsequent TCO optimization, a slight decrease in  $V_{\rm oc}$  but an increase in  $J_{\rm sc}$  can be expected.

In the conductive boundary modeling approach, the strongly nonideal effective recombination at the c-Si/a-Si interfaces requires to define an injection-dependent boundary recombination parameter  $J_0$ , fitted to lifetime measurements as explained above and parameterized as given in Appendix C. Also note that in the conductive boundary approach, the resistive losses due to current transport through the a-Si:H layers is accounted for by a (measured) contribution to the lumped series resistance.

Looking at the current loss analysis as sketched in Fig. 3, the front-contact shading is higher compared with other cells, as the grid has not been optimized toward a TCO (which is still to be optimized) yet. As expected for heterojunction solar cells, there is significant parasitic front-film absorption loss (TCO and a-Si:H), thereby reducing  $J_{\rm sc}$ . The input parameters for the HJT cell are summarized in Table V.

### E. PERL (UNSW): Record Efficiency Laboratory Silicon Solar Cell Fabricated at UNSW

The PERL cell, conceived and fabricated at the University of New South Wales (UNSW), held the 1-sun efficiency record of  $25.0 \pm 0.5\%$  between 1998 and 2014 [65], [66]. It retains the 1-sun record for a diffused-junction silicon solar cell. The input parameters presented here are based on the data published in [67]–[70].

Notably, there is a discrepancy between the  $J_{\rm sc}$  of the  $I\!-\!V$  measurement and the  $J_{\rm sc}$  calculated from the QE and reflection measurements. The latter is 0.8 mA/cm² lower, although still within the uncertainty quoted for the  $I\!-\!V$  measurement. The discrepancy might be accounted for by differences in the optics between the location of the QE, reflection, and  $I\!-\!V$  measurements. For example, the tiler's pattern introduces a strong periodic dependence of the light trapping on cell width (amplitude of 0.4 mA/cm² and a period of  $\sim\!4$   $\mu$ m); thus, a variable cell width introduces spatially variable light trapping. Other spatial variations could arise from variability in scattering associated with roughened surfaces as well as variability in the planar regions between pyramids. In Table VI, the input parameters result in a  $J_{\rm sc}$  that lies between that determined from  $I\!-\!V$  and QE measurements.

The refractive index of the original films was not published; here, we use data published in [44] and [64] to represent the original films, which yields a reflection curve consistent with the experimental curve for the stated film thicknesses.

Due to the large ratio of the perimeter-to-active cell area, the perimeter losses of the PERL cell are significant and constitute a loss in efficiency of about 0.2–0.3%, which is not taken into account in the results of Section IV. The input parameters for the PERL cell are summarized in Table VI.

### F. IBC (ANU): High-Efficiency Laboratory Interdigitated-Back-Contact Solar Cell Fabricated at ANU

ANU's IBC cell with an efficiency of  $24.4 \pm 0.7\%$  [77] is currently the most efficient IBC cell fabricated at a research institute. Although IBC cells with a higher efficiency have been

TABLE V INPUT PARAMETER SET FOR THE HJT CELL

cell size front	156 mm $ imes$ 156 mm pseudosquare thickness 150 $\mu$ m		
front	150 mm × 150 mm pseudosquare unekness 150 $\mu$ m		
	full-area i-a-Si:H/p-a-Si:H/TCO stackH-pattern screen-printed metallization		
rear	full-area i-a-S:Hi/n-a-Si:H/TCO stackfull-area screen-printed metallization		
	optics		
front TCO	70-nm ITO with $2 \times 10^{20}$ cm <sup>-3</sup> free carrier density [61]		
front a-Si:H	3.5-nm i-a-Si:H/6-nm p-a-Si:H, thicknesses from [58], optical properties from [60]		
rear TCO	150-nm ITO with $6.5 \times 10^{19}$ cm <sup>-3</sup> free carrier density [61]		
rear a-Si:H	3.5-nm i-a-Si:H/20-nm n-a-Si:H, thicknesses from [58], optical properties from [60]		
front and rear	random pyramids, 54.3° characteristic angle, 5-μm texture		
morphology	height		
busbar shading fraction	2.86%		
effective finger shading width	77 $\mu$ m ( = finger width times 70% effective shading [44])		
	metal grid from [59]		
front fingers	86 fingers with 1.7-mm-pitch, 110-μm-wide, and 13-μm-high		
	Ag-based polymer paste with 7.15- $\mu\Omega$ · cm effective resistivity		
	(derived from measured sheet resistance and assuming rectangular cross sectional profile)		
	contact resistivity $10 \ \mu\Omega \cdot \text{cm}^2$ (from [62])		
	lumped series resistance: $0.195 \ \Omega  \text{cm}^2$		
front busbars 3 busbars, 1500- $\mu$ m-wide and 13- $\mu$ m-high			
	Ag-based polymer paste with 7.15- $\mu\Omega$ · cm effective resistivity lumped series resistance: neglected		
rear metal	full area Ag-based polymer paste		
	contact resistivity $10 \ \mu\Omega \cdot \text{cm}^2$ (from [62])		
	lumped series resistance: negligible		
	electrical properties		
bulk	$5-\Omega \cdot \text{cm n-type}$		
6 (1 1	mid-gap SRH lifetimes $\tau_{\rm n}=1000~\mu{\rm s}, \tau_{\rm p}=10~000~\mu{\rm s}$		
front layers and interfaces	lumped inputs p+ boundary with sheet resistance 150 $\Omega$ (calculated from electron density and mobility given in [61])		
	parameterization of injection dependent recombination		
	parameter $J_0$ as measured and derived at SERIS, see		
	Appendix A3		
	Contribution to lumped series resistance of 0.16 $\Omega \cdot \text{cm}^2$		
	summarized in [Tables 4.2 and 4.4, p. 85/88, 58]; see		
	Appendix A1		
rear layers and interfaces	lumped inputs  n+ boundary, no value for sheet resistance required due to full area contact		
	full area contact parameterization of injection dependent recombination parameter $J_0$ as measured and derived at SERIS; see		
	Appendix A3  Negligible contribution to lumped series resistance		
	detailed inputs		
	summarized in [Tables 4.2 and 4.4, p. 85/88, 58]; see Appendix A1		

published by Sunpower (25.0% [78]) and Panasonic (25.6% with heterojunction technology [56]), a comprehensive characterization and description of their properties is not publicly available, and consequently, input parameter sets of commercial IBC cells are not presented in this work.

The properties of ANU's IBC cell have been analyzed extensively and presented in [10], [77], [79], and [80]. The largest unknown in the input parameter set is the bulk lifetime of the device as it could not be measured nondestructively. The value presented in [77] was deduced by fitting the measured *I–V* curve

TABLE VI INPUT PARAMETER SET FOR THE PERL CELL

	cell design
cell size	$2 \text{ cm} \times 2 \text{ cm}$ square
	thickness 425 $\mu$ m
front	light full area n+ diffusion
	heavy n+ diffusion underneath fingers, $6.2-\mu$ m-wide
	line contact openings, 3-\mu\text{-m\text{-m\text{-wide}}} photolithography-defined fingers, busbars outside of cell area
rear	undiffused and passivated
1041	square local n+ diffusion 30- $\mu$ m-wide, 250- $\mu$ m-pitch (266- $\mu$ m
	x-pitch and 234- $\mu$ m y-pitch for electrical unit cell modeling)
	aligned square contact openings $10$ - $\mu$ m-wide
	full-area evaporated metallization
	optics based on [69]
front dielectrics	75-nm evaporated MgF $_2$ (outer ARC layer) $n \& k$ from [71] for
	single crystal MgF <sub>2</sub> (extraordinary rays)
	30-nm evaporated ZnS (inner ARC layer) n & k from [72] for
	evaporated hexagonal ZnS (extraordinary rays) 25-nm thermal SiO <sub>2</sub> (passivation layer) $n \& k$ from [72] for
	thermal SiO <sub>2</sub> (passivation tayer) $n \ll \kappa$ from [72] for
front	regular inverted pyramids, 54.74° characteristic angle, 10 $\mu\mathrm{m}$
morphology	wide, tiler's pattern [73]
rear	planar rear with 200-nm SiO <sub>2</sub> coated with 3000-nm Al. n & k
effective finger	from [72] for thermal SiO <sub>2</sub> and pure Al. 12.8 $\mu$ m (i.e., 64% of finger width [74])
shading width	12.0 µm (i.e., 04 // of miger width [/4])
	metal grid based on [68]
front fingers	25 fingers with 800- $\mu$ m-pitch, 20- $\mu$ m-wide, and 10- $\mu$ m-high
	semicircular shape
	Ti/Pd/Al stack with $2.3-\mu\Omega \cdot \text{cm}$ effective resistivity
	contact resistivity $3-\mu\Omega \cdot cm^2$
rear metal	lumped series resistance: $0.04~\Omega \cdot \text{cm}^2$ full-area pure Ag with $1.6~\mu\Omega \cdot \text{cm}$ resistivity, $10\text{-}\mu\text{m}$ -thick
icai iliciai	contact resistivity $1-\mu\Omega \cdot \text{cm}^2$
	lumped series resistance: negligible
	electrical properties
(based o	on [70], adjusted to material properties used in this work)
bulk	$1$ - $\Omega$ · cm p-type
	mid-gap SRH lifetimes $ au_{ m n}= au_{ m p}=1200~\mu{ m s}$ (fitted to measured
1:-1-4 6	$V_{\rm oc}$ )
light front n+ diffusion	lumped inputs sheet resistance 195- $\Omega$
	recombination parameter $J_0 = 6.1 \text{ fA/cm}^2$
	depth 1- $\mu$ m
	collection efficiency 0.997 (spectrum average)
	detailed inputs
	active doping profile
	Gaussian, $5 \times 10^{18} \text{ cm}^{-3} \text{ peak}$ , $0 \text{-} \mu \text{ m} \text{ peak depth}$ , $1 \mu \text{ m}$
	deep surface SRH
	$S_{\rm p} = S_{\rm n} = 298$ cm/s derived from [75] with a texture
	multiplier of 1.7
	volume SRH
	same as in bulk
heavy front n+	lumped inputs
diffusion	sheet resistance 13 $\Omega$
	recombination parameter $J_0$
	passivated: 97 fA/cm <sup>2</sup> contacted: 118 fA/cm <sup>2</sup>
	collection efficiency 0.79 (spectrum average)
	detailed inputs
	active doping profile
	Gaussian, $1 \times 10^{20} \text{ cm}^{-3}$ peak, $0 \text{-} \mu \text{m}$ peak depth, $2 \mu \text{m}$
	deep
	surface SRH
	$S_{\rm p} = S_{\rm n} = 2000$ cm/s (passivated)
	$S_{\rm p} = S_{\rm n} = 1 \times 10^7$ cm/s (contacted, thermal velocity) volume SRH
	same as in bulk

#### TABLE VI (CONTINUED)

rear p+	lumped inputs
diffusion	sheet resistance 13.6 $\Omega$
	recombination parameter $J_0$
	passivated: 79 fA/cm <sup>2</sup>
	contacted: 130 fA/cm <sup>2</sup>
	depth 5 $\mu$ m
	collection efficiency 0.85 (uniform generation)
	detailed inputs
	active doping profile
	Gaussian, 5 $ imes$ 10 <sup>19</sup> cm <sup>-3</sup> peak, 0- $\mu$ m peak depth, 5 $\mu$ m deep
	surface SRH
	passivated: $S_p = S_n = 2000 \text{ cm/s}$
	contacted: $S_p = S_n = 1 \times 10^7$ cm/s (thermal velocity)
	volume SRH
	same as in bulk
passivated rear	lumped inputs
	$S_{\rm eff}$ : parameterization of data in [Fig. 6, 76]; see
	Appendix A3
	detailed inputs
	surface SRH and charge
	$S_{\rm p} = 20$ cm/s, $S_{\rm n} = 50$ cm/s, $Q = 7 \times 10^{10}$ cm <sup>-2</sup>

to 3-D simulation *I–V* curve where the optical and surface recombination values are experimentally determined.

Some  $J_0$  values presented in [77] have been slightly updated in this work to attain greater consistency, which notably required a reduction in the SRH lifetime in the bulk from 5 to 3 ms for a better overall agreement with measurements. There also exists some discrepancy between the measured BSF sheet resistance of 19  $\Omega$ /sq and simulation parameters in Table VII, to enable a good fit to the measured  $J_0$  [77], which could otherwise not be achieved using any reasonable assumption for the doping profile. This discrepancy is likely a combination of experimental error in the sheet resistance and  $J_0$  measurements. The change of sheet resistance is deemed insignificant to the internal resistance calculations due to the BSF being a 30- $\mu$ m diameter local diffusion around the contacts; we, therefore, choose to fit the measured  $J_0$  more accurately than the measured  $\rho_{sq}$ .

Similar as for the PERL cell, the perimeter losses of ANU's IBC cells are significant and have been characterized to contribute to 0.24% of the absolute efficiency loss, facilitated by accurate 3-D simulation based on the measured optical, electronic, and physical properties [77]. Since the simulation parameters do not include perimeter loss, this is a significant contributor to the observed discrepancy between measured and simulated efficiency, as presented in Table VIII. The input parameters for the IBC cell are summarized in Table VII.

### IV. RESULTS

We now present the major outputs attained by simulating the solar cells using the input sets provided in the previous section. These outputs are presented as *I–V* parameters (see Table VIII), *I–V* curves (see Fig. 2), external quantum efficiency curves (see Fig. 3), current losses at maximum power (see Fig. 4), and resistive losses at maximum power (see Fig. 5).

TABLE VII
INPUT PARAMETER SET FOR THE IBC CELL

	cell design				
cell size	$2 \text{ cm} \times 2 \text{ cm}$ square				
	thickness 230 $\mu$ m				
front	undiffused and passivated				
Rear	interdigitated diffusion pattern with 500- $\mu$ m-pitch				
	large-area p+ diffusion 330-μm-wide				
	circular n+ diffusions 30- $\mu$ m-wide, 70- $\mu$ m pitch				
	full-area passivation circular contact openings 7- $\mu$ m-wide and 70- $\mu$ m-pitch				
	busbars outside of cell area				
	optics				
front dielectrics	inner film				
	73-nm PECVD $SiN_x$ [80]				
	outer film				
	84-nm PECVD $SiO_x$ [80]				
front	random pyramids, 53° characteristic angle, 5- $\mu$ m texture height				
morphology rear dielectrics	inner film				
rear dietectries	30-nm thermal SiO <sub>2</sub> [72]				
	outer film				
	130-nm LPCVD Si <sub>3</sub> N <sub>4</sub> [80]				
rear morphology	Planar				
	metal grid				
p-fingers	40 fingers, $285-\mu$ m-wide and $4-\mu$ m-high				
	pure Al with 2.8- $\mu\Omega$ · cm resistivity				
	contact resistivity $20-\mu\Omega\cdot\text{cm}^2$				
	lumped series resistance: $0.016 \Omega \cdot \text{cm}^2$				
n-fingers	40 fingers, $135-\mu$ m-wide and $4-\mu$ m-high				
	pure Al with $2.8-\mu\Omega \cdot \text{cm}$ resistivity contact resistivity $15-\mu\Omega \cdot \text{cm}^2$				
	lumped series resistance: $0.035 \Omega \cdot \text{cm}^2$				
taken fr	electrical properties om [70] adjusted to material properties used in this work				
bulk	1.5-Ω · cm n-type				
	mid-gap SRH lifetimes $\tau_{\rm n}=\tau_{\rm p}=3000~\mu{\rm s}$ (best match with				
	measured I-V curve)				
p+ diffusion	lumped inputs				
	sheet resistance 166 $\Omega$				
	recombination parameter $J_0$				
	passivated: 33.2 fA/cm <sup>2</sup> contacted: 1234 fA/cm <sup>2</sup>				
	collection efficiency = 1				
	detailed inputs				
	active doping profile				
	ERFC with $5.6 \times 10^{19} \text{ cm}^{-3}$ peak, $0 \text{-} \mu \text{ m}$ peak depth,				
	$0.195$ - $\mu$ m depth factor (PC1D definition), $0.6 \mu$ m deep				
	surface SRH				
	passivated: $S_p = S_n = 6850$ cm/s (fitted to measured $J_0$ ) contacted: $S_p = S_n = 1 \times 10^7$ cm/s (thermal velocity)				
	volume SRH				
	same as in bulk				
n+ diffusion	lumped inputs				
	sheet resistance 35 $\Omega$				
	recombination parameter $J_0$				
	passivated: 176 fA/cm <sup>2</sup>				
	contacted: 202 fA/cm <sup>2</sup>				
	collection efficiency = 0.87 (uniform generation)				
	detailed inputs				
	active doping profile superposition of two ERFC's: $8 \times 10^{19}$ cm <sup>-3</sup> /4 × $10^{19}$				
	cm <sup>-3</sup> peak, 0 $\mu$ m/0 $\mu$ m peak depth, 0.2 $\mu$ m/0.5 $\mu$ m depth				
	factor (PC1D definition), 1.5 $\mu$ m deep				
	surface SRH				
	passivated: $S_{\rm p} = S_{\rm n} = 1 \times 10^6$ cm/s (fitted to measured				
	$J_0$ ) contacted: $S_p = S_n = 1 \times 10^7$ cm/s (thermal velocity)				
	volume recombination				
	1 11				

same as in bulk

TABLE VII (CONTINUED)

passivated front	lumped inputs recombination parameter $J_0 = 4.6 \text{ fA/cm}^2$
	detailed inputs
	surface SRH and charge
	$Q = 5.6 \times 10^{11} \text{ cm}^{-2}$ , $S_{\rm p} = S_{\rm n} = 2 \text{ cm/s}$ (derived from measured $J_0$ and charge, using case 3 in [81] and a texture multiplier of 1.7)
passivated rear	lumped inputs
	recombination parameter $J_0 = 19.5 \text{ fA/cm}^2$
	detailed inputs
	surface SRH and charge
	$Q = 4 \times 10^{11} \text{ cm}^{-2}$ , $S_{\rm p} = S_{\rm n} = 8 \text{ cm/s}$ (derived from measured $J_0$ and charge using case 3 in [81])

TABLE VIII
SUMMARY OF LIGHT J–V PARAMETERS SIMULATED BY QUOKKA USING
THE INPUT PARAMETERS PRESENTED IN SECTION III

cell type	$V_{\rm oc}\ [mV]$	$J_{\rm sc}[m\text{A/cm}^2]$	FF [%]	$\eta$ [%]
Conventional—simulated	626	35.2	79.8	17.6
PERC—simulated	655	39.8	79.4	20.7
n-Pasha—simulated	656	39.5	79.8	20.7
n-Pasha—measured (ECN in-house)	655	39.5	79.9	20.7
HJT—simulated	743	36.7	80.3	21.9
PERL—simulated	710	42.3	82.6	24.8
PERL—measured [66]	706	42.7	82.8	25.0
IBC—simulated	705	42.2	83.1	24.7
IBC—measured [77]	703	42.0	82.7	24.4

Measured data are included for input sets that were derived from a specific experimental solar cell.

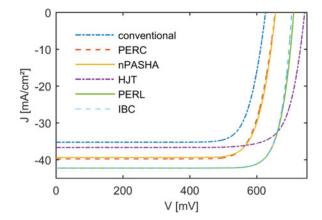


Fig. 2. Light J–V curves of the different cell types produced by Quokka simulations using the input parameters sets from this work.

The electrical component to the simulations followed the conductive boundary approach and was conducted with Quokka. The input files can be downloaded from [2]. Equivalent simulations using the detailed modeling approach (not shown) yield the same cell I–V parameters when the assumptions contained in the software are made identical and numerical errors are minimized.

We emphasize that it is not the purpose of the following comparisons to rate different cell technologies. Some of the simulations represent industrial designs while others represent

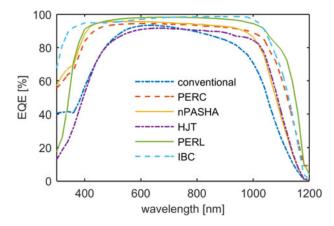


Fig. 3. External quantum efficiencies of the different cell types produced by Quokka simulations using the input parameters sets from this work; note that busbar shading is included.

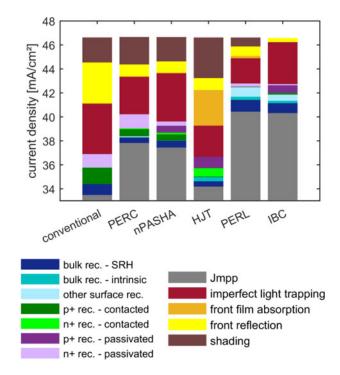


Fig. 4. Current loss breakdown at maximum power point, categorized into output current  $J_{\rm m\,pp}$ , recombination losses (*left legend*), and optical losses (*right legend*).

small-area laboratory solar cells (PERL, IBC). Thus, the results do not enable a meaningful comparison between the potential of the different cell architectures.

The results indicate that the simulated I-V parameters agree closely with those of the n-Pasha, PERL, and IBC cells that were used to represent each respective cell type. By a comparison of the losses, the relative difference between the cell types is clear. For example, the higher  $J_{\rm sc}$  of the PERL cells is due mainly to its low grid reflection and its superior light trapping. In addition, as another example, the advantage of the very high  $V_{\rm oc}$  attained by the heterojunction cell is partially offset by a high parasitic absorption in the front films.

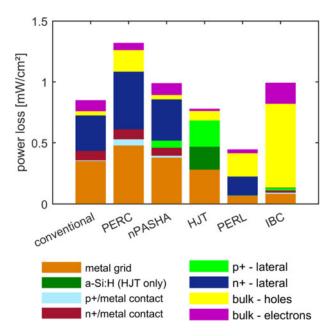


Fig. 5. Resistive power loss breakdown at maximum power point.

### V. CONCLUSION

The many intricacies inherent to solar cell modeling make it difficult—but all the more valuable—to provide a reference point on which PV researchers can base their cell simulations.

In this work, we have contributed toward that goal by providing input parameter sets to simulate six specific c-Si solar cells, as well as the methodologies, assumptions, and physical models that accompany those inputs. As far as possible, we ensure the input parameters to be justified, typical, and to produce typical and measured cell characteristics.

Once more we emphasize that the parameter sets cannot be used to represent all cells of a given architecture. Some sets are specific to small-area laboratory-based cells, others to large-area industrial cells. In addition, due to variability in material quality and imperfect manufacturing repeatability, the parameter sets represent just one cell within a wide distribution of cells made by identical processing sequences. Moreover, changes to the input sets and methodologies cannot be made indiscriminately. Many input values depend on the choice of physical model, e.g., the values selected for the surface recombination velocities depend on the Auger and bandgap narrowing model. Simulation experts are encouraged to critically examine the justifications and substitute their own values where appropriate.

The input sets are accessible from an online library [2]. We hope that through examination, discussion, and experimentation, they will be continually reviewed, revised, and extended to provide an up-to-date reference for the PV community to simulate c-Si solar cells with ever more accuracy.

## APPENDIX A INPUT PARAMETERS FOR DETAILED MODELING OF THE HJT (PROJECTED) CELL

For better accessibility, excerpts of [Tables 4.2 and 4.4, 58] are given in Tables IX and X, which list the electrical input

TABLE IX EXCERPT OF [TABLE 4.2, 58]

Parameters	a-Si:H(i)	a-Si:H(n)	a-Si:H(p)
Layer thickness (μm)	0.005	0.020	0.020
Electron affinity (eV)	4.0	4.0	4.0
Mobility gap (eV)	1.75	1.80	1.75
$\Delta E_V$ with respect to c-Si (eV)	-0.41	-0.46	-0.41
Donor (acceptor) doping (cm <sup>-3</sup> )	0	$1.45 \times 10^{19}$	$(1.41 \times 10^{19})$
Effective DOS in CB (cm <sup>-3</sup> )	$2 \times 10^{20}$	$2 \times 10^{20}$	$2 \times 10^{20}$
Effective DOS in VB (cm <sup>-3</sup> )	$2 \times 10^{20}$	$2 \times 10^{20}$	$2 \times 10^{20}$
Urbach energy (VB tail) (eV)	0.045	0.05	0.05
Urbach energy (CB tail) (eV)	0.03	0.03	0.03
Urbach tail pre- factor(cm <sup>-3</sup> · eV <sup>-1</sup> )	$4 \times 10^{21}$	$4\times10^{21}$	$4\times10^{21}$
Electron/hole mobility $(cm^2 \cdot V^{-1} \cdot s^{-1})$	25/5	20/4	25/5
Gaussian defect density (cm <sup>-3</sup> ) Gaussian donor peak position	9 × 10 <sup>16</sup>	$2.75 \times 10^{19}$	$2.63 \times 10^{19}$
from VB (eV)	0.83	0.50	1.00
Gaussian acceptor peak position from VB (eV)	1.03	0.70	1.20
Neutral $\sigma$ (for			
Urbach tail and Gaussian defects) (cm <sup>2</sup> )	$10^{-15}$	$6.5 \times 10^{-16}$	$6.5 \times 10^{-16}$
Charged $\sigma$ (for Urbach tail and Gaussian defects) (cm <sup>2</sup> )	$10^{-14}$	$6.5 \times 10^{-15}$	$6.5 \times 10^{-15}$
Activation energy (eV)	0.83	0.20	0.30
Correlation energy (eV)	0.20	0.20	0.20

TABLE X [TABLE 4.4, 58]

Lifetime structure	[i/N/i] c-Si(n)/a-Si:H(i)	[p/i/N/i/p] c-Si(n)/a-Si:H(i, p)	$ \begin{array}{c} [n/i/N/i/n] \\ c\text{-Si}(n)/a\text{-Si}:H(i,n) \end{array}$
Interface $D_{it}$ $(cm^{-2} \cdot eV^{-1})$	a-Si/c-Si interface $4.6 \times 10^{12}$	a-Si/c-Si interface $5 \times 10^{10}$	a-Si/c-Si interface $5 \times 10^{10}$
Charged $\sigma$ (cm <sup>2</sup> ) Neutral $\sigma$ (cm <sup>2</sup> )	$10^{-18} \\ 10^{-19}$	$10^{-18} \\ 10^{-19}$	$10^{-18} \\ 10^{-19}$

parameters for the detailed modeling of the a-Si:H films and interfaces as used for the HJT cell.

### APPENDIX B DOPING PROFILES

Figs. 6 and 7 show the emitter and BSF profiles of the conventional and PERC cell type assumed in this work.

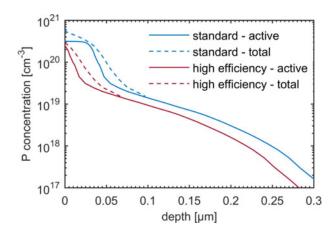


Fig. 6. Phosphorous concentration profiles of the front  $n^+$  regions (emitter) of the "standard" (taken from [38]) and "high efficiency" emitter as used for the conventional and PERC cell type, respectively; note that the "high efficiency" profile is derived by thinning the "standard" profile by 30 nm, representing an etch-back process.

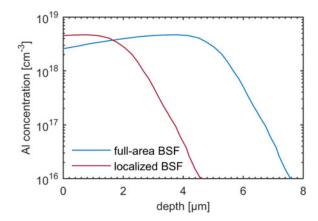


Fig. 7. Al concentration profiles of the rear  $p^+$  regions (BSF) of the full-area BSF (conventional cell) and local BSF region (PERC cell); note that the local BSF profile is derived by thinning the full-area one by 3  $\mu m$ .

### APPENDIX C PARAMETERIZATIONS

### A. Front and Rear $J_0$ of HJT (Projected) Cell

The injection-dependent  $J_0$  of the a-Si:H boundaries were extracted by numerical simulations of measured effective lifetime, which also match the detailed modeling, and numerically fitted by a second-order Fourier expression. Here,  $\Delta p[\mathrm{cm}^{-3}]$  denotes the excess carrier density at the boundary

$$J_{o,\text{front}} \left[ \frac{A}{\text{cm}^2} \right] = \left( \frac{8.27}{8.52} \right)^2$$

$$\cdot 10^{\land} \left( (1.367 + 0.7028 \cos(\log(\Delta p)) + 0.2459 \sin(\log(\Delta p)) - 0.04068 \cos(2\log(\Delta p)) - 0.2271 \sin(2\log(\Delta p)) \right)$$

$$J_{o,\text{rear}} \left[ \frac{A}{\text{cm}^2} \right] = \left( \frac{8.27}{8.52} \right)^2$$

$$\cdot 10^{\ \ \ } (1.029 + 0.293 \cos(1.304 \log(\Delta p))$$

$$- 0.5323 \sin(1.304 \log(\Delta p))$$

$$+ 0.01279 \cos(2.608 \log(\Delta p))$$

$$+ 0.1621 \sin(2.608 \log(\Delta p))).$$

### B. Rear $S_{\text{eff}}$ of the PERL (UNSW) Cell

The best fit to the data in [Fig. 6, 76] was achieved by the following double exponential function, where  $\Delta n [\text{cm}^{-3}]$  denotes the excess carrier density at the boundary:

$$S_{\text{eff}} \left[ \frac{\text{cm}}{\text{s}} \right] = 10^{\land} \left( 3.262 \times 10^{14} \right)$$

$$\exp \left( -\left( \frac{\log (\Delta n) + 395.3}{71.14} \right)^{2} \right)$$

$$+ 1.35 \exp \left( -\left( \frac{\log (\Delta n) - 10.88}{2.229} \right)^{2} \right).$$

#### REFERENCES

- A. Fell et al., "Input parameters for the simulation of silicon solar cells in 2014," presented at the 6th World Conf. Photovoltaic Energy Convers., Kyoto, Japan, 2014.
- [2] (2015). PV Lighthouse Solar Cell Library. [Online]. Available: http://pvlighthouse.com.au/resources/solar%20cell%20library/solar%20cell%20library.aspx
- [3] Synopsys, Sentaurus: Sentaurus Device User Guide, Release H-2013.03, 2013
- [4] (2015). PV Lighthouse. [Online]. Available: http://pvlighthouse.com.au
- [5] S. C. Baker-Finch and K. R. McIntosh, "One-dimensional photogeneration profiles in silicon solar cells with pyramidal texture," *Progr. Photovoltaics: Res. Appl.*, vol. 20, pp. 51–61, 2012.
- [6] A. Fell and K. R. McIntosh, "Deriving the generation profile for silicon solar cells from lumped optical parameters," presented at the 42rd IEEE Photovoltaic Spec. Conf., New Orleans, LA, USA, 2015.
- [7] P. A. Basore, "Numerical modeling of textured silicon solar cells using PC-1D," *IEEE Trans. Electron Devices*, vol. 37, no. 2, pp. 337–343, Feb. 1990.
- [8] A. Fell, "A free and fast three-dimensional/two-dimensional solar cell simulator featuring conductive boundary and quasi-neutrality approximations," *IEEE Trans. Electron Devices*, vol. 60, no. 2, pp. 733–738, Feb. 2013.
- [9] A. Goetzberger, J. Knobloch, B. Voss, and R. Waddington, *Crystalline Silicon Solar Cells*. Chichester, U.K.: Wiley, 1998.
- [10] A. Fell, K. C. Fong, K. R. McIntosh, E. Franklin, and A. W. Blakers, "3-D simulation of interdigitated-back-contact silicon solar cells with quokka including perimeter losses," *IEEE J. Photovoltaics*, vol. 4, no. 4, pp. 1040– 1045. Jul. 2014.
- [11] R. Brendel, "Modeling solar cells with the dopant-diffused layers treated as conductive boundaries," *Progr. Photovoltaics: Res. Appl.*, vol. 20, pp. 31–43, 2012.
- [12] P. A. Basore and K. Cabanas-Holmen, "PC2D: A circular-reference spreadsheet solar cell device simulator," *IEEE J. Photovoltaics*, vol. 1, no. 1, pp. 72–77, Jul. 2011.
- [13] A. Cuevas and R. A. Sinton, "Detailed modelling of silicon solar cells," in *Proc. 23rd Eur. Photovoltaic Sol. Energy Conf.*, Valencia, Spain, 2008, pp. 315–319.
- [14] A. Cuevas, "Physical model of back line-contact front-junction solar cells," J. Appl. Phys., vol. 113, p. 164502, 2013.
- [15] (2014). Atlas Device Simulator, Silvaco Int. Softw., Santa Clara, CA, USA.

- [16] K. R. McIntosh and P. P. Altermatt, "A freeware 1D emitter model for silicon solar cells," in *Proc. 35th IEEE Photovoltaic Spec. Conf.*, 2010, pp. 002188–002193.
- [17] M. Padilla et al., "Surface recombination parameters of interdigitated-back-contact silicon solar cells obtained by modeling luminescence images," Sol. Energy Mater. Sol. Cells, vol. 120, Part A, pp. 363–375, 2014.
- [18] K. Rapolu, P. Singh, and S. Shea, "Two dimensional numerical modeling of a silicon solar cell with selective emitter configuration," in *Proc. 35th IEEE Photovoltaic Spec. Conf.*, 2010, pp. 002227–002232.
- [19] D. A. Clugston and P. A. Basore, "PC1D version 5: 32-bit solar cell modeling on personal computers," in *Proc. 26th IEEE Photovoltaic Spec. Conf.*, 1997, pp. 207–210.
- [20] H. Haug, A. Kimmerle, J. Greulich, A. Wolf, and E. Stensrud Marstein, "Implementation of Fermi–Dirac statistics and advanced models in PC1D for precise simulations of silicon solar cells," *Sol. Energy Mater. Sol. Cells*, vol. 131, pp. 30–36, Dec. 2014.
- [21] P. P. Altermatt, "Models for numerical device simulations of crystalline silicon solar cells—A review," *J. Comput. Electron.*, vol. 10, pp. 314–330, Sep. 2011.
- [22] D. E. Kane and R. M. Swanson, "Measurement of the emitter saturation current by a contactless photoconductivity decay method," in *Proc. 18th IEEE Photovoltaic Spec. Conf.*, 1985, pp. 578–583.
- [23] K. Misiakos and D. Tsamakis, "Accurate measurements of the silicon intrinsic carrier density from 78 to 340 K," J. Appl. Phys., vol. 74, pp. 3293–3297, 1993.
- [24] P. P. Altermatt, A. Schenk, F. Geelhaar, and G. Heiser, "Reassessment of the intrinsic carrier density in crystalline silicon in view of band-gap narrowing," *J. Appl. Phys.*, vol. 93, pp. 1598–1604, 2003.
- [25] A. Schenk, "Finite-temperature full random-phase approximation model of band gap narrowing for silicon device simulation," *J. Appl. Phys.*, vol. 84, pp. 3684–3695, 1998.
- [26] A. Richter, S. W. Glunz, F. Werner, J. Schmidt, and A. Cuevas, "Improved quantitative description of Auger recombination in crystalline silicon," *Phys. Rev. B*, vol. 86, p. 165202, 2012.
- [27] T. Trupke et al., "Temperature dependence of the radiative recombination coefficient of intrinsic crystalline silicon," J. Appl. Phys., vol. 94, pp. 4930–4937, 2003.
- [28] D. B. M. Klaassen, "A unified mobility model for device simulation—I. Model equations and concentration dependence," *Solid-State Electron.*, vol. 35, pp. 953–959, 1992.
- [29] C. Gueymard, SMARTS2: A Simple Model of the Atmospheric Radiative Transfer of Sunshine: Algorithms and Performance Assessment, Cocoa, FL, USA: Florida Solar Energy Cent., 1995.
- [30] M. A. Green, "Self-consistent optical parameters of intrinsic silicon at 300K including temperature coefficients," Sol. Energy Mater. Sol. Cells, vol. 92, pp. 1305–1310, 2008.
- [31] S. P. Group, International Technology Roadmap for Photovoltaic, Mar. 2014
- [32] M. Abbott, G. Scardera, K. R. McIntosh, and A. Meisel, "Simulation of emitter doping profiles formed by industrial POCl3 processes," in *Proc. IEEE 39th Photovoltaic Spec. Conf.*, 2013, pp. 1383–1388.
- [33] Y. Li, Z. Li, Y. Zhao, and A. Lennon, "Modelling of light trapping in acidic-textured multicrystalline silicon wafers," *Int. J. Photoenergy*, vol. 2012, p. 369101, 2012.
- [34] S. C. Baker-Finch, K. R. McIntosh, and M. L. Terry, "Isotextured silicon solar cell analysis and modeling 1: Optics," *IEEE J. Photovoltaics*, vol. 2, no. 4, pp. 457–464, Oct. 2012.
- [35] J. Greulich et al., "Optical simulation and analysis of iso-textured silicon solar cells including light trapping," presented at the 5th Int. Conf. Crystalline Silicon Photovoltaics, Constance, Germany, 2015.
- [36] B. T. Phong, "Illumination for computer generated pictures," Commun. ACM, vol. 18, pp. 311–317, 1975.
- [37] M. Abbott et al., "Silicon ink selective emitter solar cells on multicrystalline silicon wafers," presented at the 25th Photovoltaic Sol. Energy Conf. Exhib. Conf., Valencia, Spain, 2010.
- [38] A. Dastgheib-Shirazi, M. Steyer, G. Micard, H. Wagner, P. P. Altermatt, and G. Hahn, "Relationships between diffusion parameters and phosphorus precipitation during the POCl<sub>3</sub> diffusion process," *Energy Procedia*, vol. 38, pp. 254–262, 2013.
- [39] B. Min, H. Wagner, A. Dastgheib Shirazi, A. Kimmerle, H. Kurz, and P. P. Altermatt, "Heavily doped Si: P emitters of crystalline Si solar cells: recombination due to phosphorus precipitation," *Phys. Status Solidi (RRL)—Rapid Res. Lett.*, vol. 8, pp. 680–684, 2014.

- [40] R. Bock, P. P. Altermatt, J. Schmidt, and R. Brendel, "Formation of aluminum-oxygen complexes in highly aluminum-doped silicon," *Semi-cond. Sci. Technol.*, vol. 25, p. 105007, 2010.
- [41] M. Rüdiger, M. Rauer, C. Schmiga, and M. Hermle, "Effect of incomplete ionization for the description of highly aluminum-doped silicon," *J. Appl.* phys., vol. 110, p. 024508, 2011.
- [42] P. Rosenits, T. Roth, and S. W. Glunz, "Erratum on "Determining the defect parameters of the deep aluminum-related defect center in silicon [Appl. Phys. Lett. 91, 122109 (2007)]," Appl. Phys. Lett., vol. 99, p. 239904, 2011.
- [43] S. Duttagupta, F. Ma, B. Hoex, T. Mueller, and A. G. Aberle, "Optimised antireflection coatings using silicon nitride on textured silicon surfaces based on measurements and multidimensional modelling," *Energy Proce*dia, vol. 15, pp. 78–83, 2012.
- [44] R. Woehl, M. Hörteis, and S. Glunz, "Determination of the effective optical width of screen printed and aerosol printed and plated fingers," in *Proc.* 23rd Eur. Photovoltaic Sol. Energy Conf. Exhib., 2008, pp. 1377–1382.
- [45] M. Rüdiger, C. Schmiga, M. Rauer, M. Hermle, and S. W. Glunz, "Efficiency potential of n-type silicon solar cells with aluminum-doped rear p+ emitter," *IEEE Trans. Electron Devices*, vol. 59, no. 5, pp. 1295–1303, May 2012.
- [46] M. Rüdiger, C. Schmiga, M. Rauer, M. Hermle, and S. W. Glunz, "Optimisation of industrial n-type silicon solar cells with aluminium-alloyed rear emitter by means of 2D numerical simulation," in *Proc. 25th Eur. Photovoltaic Sol. Energy Conf. Exhib.*, Valencia, Spain, 2010, pp. 2280–2286.
- [47] J. Schmidt et al., "Impurity-related limitations of next-generation industrial silicon solar cells," in Proc. IEEE 38th Photovoltaic Spec. Conf., 2012, pp. 1–5.
- [48] J. Greulich, N. Wöhrle, M. Glatthaar, and S. Rein, "Optical modeling of the rear surface roughness of passivated silicon solar cells," *Energy Procedia*, vol. 27, pp. 234–239, 2012.
- [49] N. Wohrle, J. Greulich, C. Schwab, M. Glatthaar, and S. Rein, "A predictive optical simulation model for the rear-surface roughness of passivated silicon solar cells," *IEEE J. Photovoltaics*, vol. 3, no. 1, pp. 175–182, Jan. 2013.
- [50] S. C. Baker-Finch, K. R. McIntosh, M. L. Terry, and Y. Wan, "Isotextured silicon solar cell analysis and modeling 2: Recombination and device modeling," *IEEE J. Photovoltaics*, vol. 2, no. 4, pp. 465–472, Oct. 2012.
- [51] P. Saint-Cast, D. Kania, M. Hofmann, J. Benick, J. Rentsch, and R. Preu, "Very low surface recombination velocity on p-type c-Si by high-rate plasma-deposited aluminum oxide," *Appl. Phys. Lett.*, vol. 95, pp. 151502-1–151502-3, 2009.
- [52] L. E. Black and K. R. McIntosh, "Modeling recombination at the Si–AlO interface," *IEEE J. Photovoltaics*, vol. 3, no. 3, pp. 936–943, Jul. 2013.
- [53] I. Romijn, A. Gutjahr, D. Saynova, J. Anker, E. Kossen, and K. Tool, "Cost effective n-Pasha solar cells with efficiency above 20%," *Photovoltaics Int.*, vol. 20, pp. 33–40, 2013.
- [54] A. Burgers et al., "19.5% efficient n-type Si solar cells made in production," in Proc. 26th Eur. Photovoltaic Sol. Energy Conf., 2011, pp. 1144–1147.
- [55] G. J. M. Janssen, A. Gutjahr, A. R. Burgers, D. S. Saynova, I. Cesar, and I. G. Romijn, "Power loss analysis of n-PASHA cells validated by 2D simulations," in *Proc. 28th Eur. Photovoltaic Sol. Energy Conf. Exhib.*, Paris, France, 2013, pp. 1548–1553.
- [56] K. Masuko et al., "Achievement of more than 25% conversion efficiency with crystalline silicon heterojunction solar cell," *IEEE J. Photovoltaics*, vol. 4, no. 6, pp. 1433–1435, Nov. 2014.
- [57] M. A. Green, K. Emery, Y. Hishikawa, W. Warta, and E. D. Dunlop, "Solar cell efficiency tables (version 42)," *Progr. Photovoltaics: Res. Appl.*, vol. 21, pp. 827–837, 2013.
- [58] L. Zhepeng, "Design, fabrication and characterisation of thin-film materials for heterojunction silicon wafer solar cells," Ph.D. dissertation, Dept. Elect. Comput. Eng., Univ. Singapore, Singapore, 2014.
- [59] A. Khanna, Z. P. Ling, V. Shanmugam, M. B. Boreland, I. Hayashi, D. Kirk et al., "Screen printed metallisation for silicon heterojunction solar cells," in Proc. 28th Eur. Photovoltaic Sol. Energy Conf. Exhib., Paris, France, 2013, pp. 1336–1339.
- [60] Z. C. Holman, A. Descoeudres, L. Barraud, F. Z. Fernandez, J. P. Seif, S. De Wolf *et al.*, "Current losses at the front of silicon heterojunction solar cells," *IEEE J. Photovoltaics*, vol. 2, no. 1, pp. 7–15, Jan. 2012.

- [61] Z. C. Holman, M. Filipič, A. Descoeudres, S. De Wolf, F. Smole, M. Topič et al., "Infrared light management in high-efficiency silicon heterojunction and rear-passivated solar cells," J. Appl. Phys., vol. 113, p. 013107, 2013.
- [62] J. Geissbuhler, S. De Wolf, A. Faes, N. Badel, Q. Jeangros, A. Tomasi et al., "Silicon heterojunction solar cells with copper-plated grid electrodes: Status and comparison with silver thick-film techniques," *IEEE J. Photovoltaics*, vol. 4, no. 4, pp. 1055–1062, Jul. 2014.
- [63] M. Rahmouni, A. Datta, P. Chatterjee, J. Damon-Lacoste, C. Ballif, and P. R. I Cabarrocas, "Carrier transport and sensitivity issues in heterojunction with intrinsic thin layer solar cells on N-type crystalline silicon: A computer simulation study," *J. Appl. Phys.*, vol. 107, p. 054521, 2010.
- [64] M. Taguchi, E. Maruyama, and M. Tanaka, "Temperature dependence of amorphous/crystalline silicon heterojunction solar cells," *Jpn. J. Appl. Phys.*, vol. 47, p. 814, 2008.
- [65] J. Zhao, A. Wang, M. A. Green, and F. Ferrazza, "19.8% efficient "honey-comb" textured multicrystalline and 24.4% monocrystalline silicon solar cells," *Appl. Phys. Lett.*, vol. 73, pp. 1991–1993, 1998.
- [66] J. Zhao, A. Wang, and M. A. Green, "24 · 5% efficiency silicon PERT cells on MCz substrates and 24 · 7% efficiency PERL cells on FZ substrates," *Progr. Photovoltaics: Res. Appl.*, vol. 7, pp. 471–474, 1999.
- [67] A. G. Aberle, P. P. Altermatt, G. Heiser, S. J. Robinson, A. Wang, J. Zhao, et al., "Limiting loss mechanisms in 23% efficient silicon solar cells," J. Appl. Phys., vol. 77, pp. 3491–3504, 1995.
- [68] P. P. Altermatt, G. Heiser, A. G. Aberle, A. Wang, J. Zhao, S. J. Robinson, et al., "Spatially resolved analysis and minimization of resistive losses in high-efficiency Si solar cells," *Progr. Photovoltaics: Res. Appl.*, vol. 4, pp. 399–414, 1996.
- [69] J. Zhao and M. A. Green, "Optimized antireflection coatings for high-efficiency silicon solar cells," *IEEE Trans. Electron Devices*, vol. 38, no. 8, pp. 1925–1934, Aug. 1991.
- [70] P. P. Altermatt, G. Heiser, and M. A. Green, "Numerical quantification and minimization of perimeter losses in high-efficiency silicon solar cells," *Progr. Photovoltaics: Res. Appl.*, vol. 4, pp. 355–367, 1996.
- [71] M. J. Dodge, "Refractive properties of magnesium fluoride," Appl. Opt., vol. 23, pp. 1980–1985, 1984.
- [72] E. D. Palik, Ed., Handbook of Optical Constants of Solids (Academic Press Handbook Series), vol. 1. New York, NY, USA: Academic, 1985.
- [73] P. Campbell and M. A. Green, "Light trapping properties of pyramidally textured surfaces," J. Appl. Phys., vol. 62, pp. 243–249, 1987.
- [74] A. Blakers, "Shading losses of solar-cell metal grids," J. Appl. Phys., vol. 71, pp. 5237–5241, 1992.
- [75] P. P. Altermatt, J. O. Schumacher, A. Cuevas, M. J. Kerr, S. W. Glunz, R. R. King, et al., "Numerical modeling of highly doped Si:P emitters based on Fermi–Dirac statistics and self-consistent material parameters," J. Appl. Phys., vol. 92, pp. 3187–3197, 2002.
- [76] S. J. Robinson, S. R. Wenham, P. P. Altermatt, A. G. Aberle, G. Heiser, and M. A. Green, "Recombination rate saturation mechanisms at oxidized surfaces of high-efficiency silicon solar cells," *J. Appl. Phys.*, vol. 78, pp. 4740–4754, 1995.
- [77] E. Franklin, et al., "Design, fabrication and characterisation of a 24.4% efficient interdigitated back contact solar cell," Progr. Photovoltaics: Res. Appl., 2014. doi: 10.1002/pip.2556
- [78] D. D. Smith, P. Cousins, S. Westerberg, R. D. Jesus-Tabajonda, G. Aniero, and Y. Shen, "Toward the practical limits of silicon solar cells," *IEEE J. Photovoltaics*, vol. 4, no. 6, pp. 1465–1469, Nov. 2014.
- [79] K. C. Fong, K. Teng, K. R. McIntosh, A. W. Blakers, E. Franklin, N. Zin, et al., "N+ diffusion and contact optimisation of IBC solar cells," presented at the 28th Eur. PV Sol. Energy Conf., Paris, France, 2013.
- [80] K. R. McIntosh et al., "Quantifying the optical losses in back-contact solar cells," in Proc. IEEE 40th Photovoltaic Spec. Conf., 2014, pp. 0115–0123.
- [81] K. R. McIntosh and L. E. Black, "On effective surface recombination parameters," J. Appl. Phys., vol. 116, pp. 014503, 2014.

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